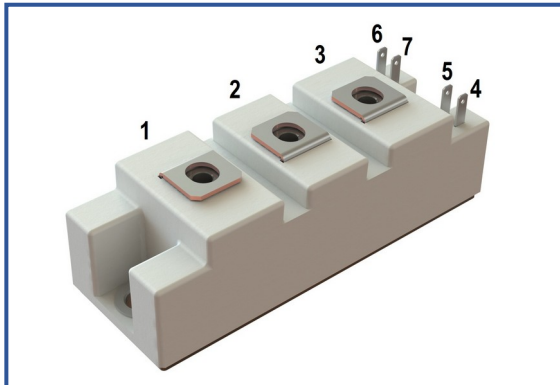


Industry standart 34mm IGBT module

1700 V 100 A



Chip features

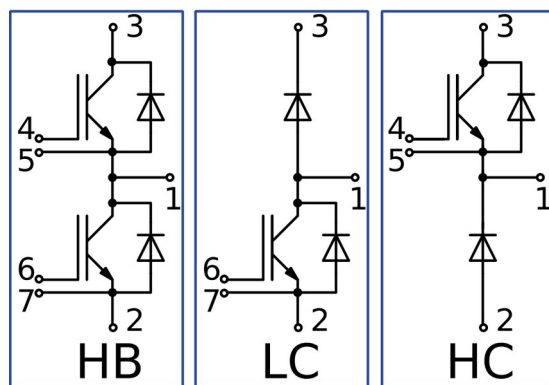
- IGBT chip
 - Trench FS
 - low $V_{CE(sat)}$ value
 - 10 μ s short circuit of 150°C
 - square RBSOA of 2xI_c
 - low EMI
- FRD chip
 - fast and soft reverse recovery
 - low voltage drop

Design features

- copper baseplate
- Al₂O₃ DBC substrate
- ultrasonically welded power terminals
- Improved thermal cycling
- RoHS compliant
- UL certified file-No. E255404

Typical application

- AC motor drives
- solar inverter
- air conditioning
- high power converters and UPS



Maximum rated values

Definition	Symbol	Conditions	Value	Unit
IGBT				
Collector-Emitter voltage	V_{CES}	$V_{GE} = 0$.	1700	V
Collector current (nominal)	$I_{C\ nom}$		100	A
Collector current (maximum continuous)	$I_{C\ 25}$	$T_{vj\ (max)} = 175^{\circ}C; T_c = 25^{\circ}C$.	160	A
	$I_{C\ 80}$	$T_{vj\ (max)} = 175^{\circ}C; T_c = 80^{\circ}C$.	100	A
Repetitive peak collector current*1	I_{CRM}	$I_{CRM} = 3 \times I_{C\ nom}; t_p = 1\ ms$.	300	A
Short-circuit duration	t_{psc}	$T_{vj} = 25^{\circ}C; V_{GE} = \pm 15\ V; V_{CE} = 1000\ V;$ $R_{G\ on} = R_{G\ off} = 2.2\ \Omega; I_{Cmax} < 700\ A$.	10	μ s
		$T_{vj} = 150^{\circ}C; V_G = \pm 15\ V; V_{CE} = 1000V;$ $R_{G\ on} = R_{G\ off} = 2.2\ \Omega; I_{Cmax} < 680\ A$.	10	
Gate-Emitter voltage	V_{GES}		± 20	V
Junction operating temperature	$T_{vj\ (op)}$		-40...+150	°C
Inverse diode \ Freewheeling diode				
Repetitive peak reverse voltage	V_{RRM}	$V_{GE} = 0\ V$.	1700	V
Forward current (nominal)	$I_{F\ nom}$		100	A
Forward current (maximum continuous)	$I_{F\ 25}$	$T_{vj\ (max)} = 175^{\circ}C; T_c = 25^{\circ}C$.	125	A
	$I_{F\ 80}$	$T_{vj\ (max)} = 175^{\circ}C; T_c = 80^{\circ}C$.	93	A
Repetitive peak forward current*1	I_{FRM}	$I_{FRM} = 3 \times I_{F\ nom}; t_p = 1\ ms$.	300	A
Junction operating temperature	$T_{vj\ (op)}$		-40...+150	°C
Module				
Storage temperature	T_{stg}		-55...+50	°C
Isolation voltage	U_{isol}	AC sin 50 Hz; t = 1 min.	4000	V

*1 Pulse width and repetition rate should be such that device junction temperature does not exceed maximum T_{vj} rating.

Characteristics

Definition	Symbol	Conditions	Value			Unit.		
			min.	typ.	max.			
IGBT								
Collector-Emitter saturation voltage	V_{CEsat}	$V_{GE} = +15\text{ V}; I_C = 100\text{ A}; t_u = 1000\ \mu\text{s}.$	$T_{vj} = 25^\circ\text{C}$	2.03	2.07	2.47	V	
			$T_{vj} = 150^\circ\text{C}$	2.66	2.72	2.92	V	
Gate-Emitter threshold voltage	$V_{GE(th)}$	$I_C = 4\text{ mA}; V_{CE} = V_{GE}; T_{vj} = 25^\circ\text{C}; t_u = 2\text{ ms}.$		5.28	5.72	6.35	V	
Collector-Emitter cut-off current	I_{CES}	$V_{CE} = 1700\text{ V}; t_u = 50\text{ ms}; V_{GE} = 0.$	$T_{vj} = 25^\circ\text{C}$	3.95	4.60	300	μA	
			$T_{vj} = 150^\circ\text{C}$	0.55	0.67	2.00	mA	
Gate-Emitter leakage current	I_{GES}	$V_{CE} = 0; V_{GE} = \pm 20\text{ V}; T_{vj} = 25^\circ\text{C}; t_u = 30\text{ ms}.$		16.9	22.1	500	nA	
Input capacitance	C_{ies}	$V_{CE} = 10\text{ V}; V_{GE} = 0\text{ V}; f = 1\text{ MHz}; T_{vj} = 25^\circ\text{C}.$		-	7.50	-	nF	
Output capacitance	C_{oes}			-	0.40	-	nF	
Reverse transfer capacitance	C_{res}			-	0.50	-	nF	
Total gate charge	Q_G	$I_C = 100\text{ A}; V_{CE} = 920\text{ V}; V_{GE} = -8 \div 15\text{ V}.$		-	1197	1271	nC	
Internal gate resistance	R_{Gint}	$T_{vj} = 25^\circ\text{C}.$		-	10.0	-	Ω	
Turn-on delay time	$t_{d(on)}$	$V_{CE} = 920\text{ V}; V_{GE} = \pm 15\text{ V}; I_{Cmax} = 100\text{ A}; R_G = 2.2\ \Omega; L = 56\text{ nH}.$	$T_{vj} = 25^\circ\text{C}$	352	360	420	ns	
			$T_{vj} = 150^\circ\text{C}$	404	412	480		
Rise time	t_{ri}		$T_{vj} = 25^\circ\text{C}$	33.0	34.0	45.0	ns	
			$T_{vj} = 150^\circ\text{C}$	38.0	39.0	50.0		
Turn-on energy	E_{on}		$T_{vj} = 25^\circ\text{C}$	10.0	12.0	18.0	mJ	
			$T_{vj} = 150^\circ\text{C}$	18.0	21.0	28.0		
Turn-off delay time	$t_{d(off)}$		$T_{vj} = 25^\circ\text{C}$	400	410	480	ns	
			$T_{vj} = 150^\circ\text{C}$	480	480	560		
Fall time	t_{fi}		$T_{vj} = 25^\circ\text{C}$	556	588	720	ns	
			$T_{vj} = 150^\circ\text{C}$	788	832	960		
Turn-off energy	E_{off}		$T_{vj} = 25^\circ\text{C}$	20.0	22.0	27.0	mJ	
			$T_{vj} = 150^\circ\text{C}$	29.0	31.0	39.0		
Collector-emitter threshold voltage	V_{CE0}	$V_{GE} = +15\text{ V}; T_{vj} = 150^\circ\text{C};$		1.04	1.06	1.10	V	
On-State slope resistance (IGBT)	r_{CE0}	$I_{CE1} = 25\text{ A}; I_{CE2} = 100\text{ A}; t_u = 1000\ \mu\text{s}.$		16.1	16.7	18.0	m Ω	
Thermal resistance junction to case	$R_{th(j-c)}$	DC; $I_{CE} = 100 \pm 10\text{ A}; I_{test} = 0.5\text{ A}; V_{GE} = +15\text{ V}.$		-	0.209	0.235	K/W	
Inverse diode \ Freewheeling diode								
Forward voltage drop	V_F	$I_F = 100\text{ A}; V_{GE} = 0; t_u = 1000\ \mu\text{s}.$	$T_{vj} = 25^\circ\text{C}$	1.83	1.87	2.22	V	
			$T_{vj} = 150^\circ\text{C}$	1.89	1.95	2.34	V	
Reverse recovery time	t_{rr}	$V_{GE} = \pm 15\text{ V}; V_{CE} = 920\text{ V}; I_{Cmax} = 100\text{ A}; R_{Gon} = 2.2\ \Omega; L = 56\text{ nH}.$	$T_{vj} = 25^\circ\text{C}$	133	148	180	ns	
			$T_{vj} = 150^\circ\text{C}$	211	269	340	ns	
Repetitive peak reverse current	I_{RRM}		$T_{vj} = 25^\circ\text{C}$	132	139	170	A	
			$T_{vj} = 150^\circ\text{C}$	146	156	190	A	
Reverse recovered charge	Q_{rr}		$T_{vj} = 25^\circ\text{C}$	10.0	11.0	15.0	μC	
			$T_{vj} = 150^\circ\text{C}$	17.0	20.0	26.0	μC	
Reverse recovery energy	E_{rec}		$T_{vj} = 25^\circ\text{C}$	10.0	11.0	15.0	mJ	
			$T_{vj} = 150^\circ\text{C}$	20.0	22.0	27.0	mJ	
Threshold voltage	$V_{(TO)}$		$T_{vj} = 150^\circ\text{C}; V_{GE} = 0; I_{CE1} = 25\text{ A};$		0.89	0.90	0.95	V
Forward slope resistance	r_T		$I_{CE2} = 100\text{ A}; t_u = 1000\ \mu\text{s}$		10.0	10.5	11.6	m Ω
Thermal resistance junction to case	$R_{th(jc-D)}$		DC; $I_{CE} = 80 \pm 10\text{ A}; I_{test} = 0.5\text{ A}; V_{GE} = +15\text{ V}.$		-	0.452	0.500	K/W

MIFA-HB17FA-100N

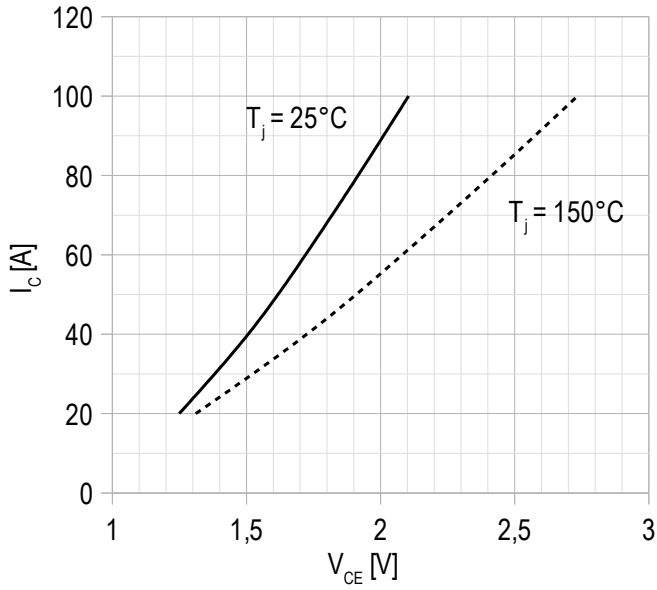
IGBT module datasheet

Module							
Pin resistance	R_{Pxy}	$T_{vj} = 25^{\circ}\text{C}$.	R_{P12}	-	0.47	0.50	m Ω
			R_{P13}	-	0.66	0.66	
Parasitic inductance between terminals	L_{Pce}			-	27	-	nH
Thermal resistance case to heatsink	R_{thCH}	per module		-	0.02	0.04	K/W
Mounting torque for screws to heatsink	M_s	to heatsink M6		3	-	5.00	N*m
Mounting torque for terminal screws	M_t	to terminals M5		1.80	2.00	2.20	N*m
Weight	W			-	153	170	g

Notes:

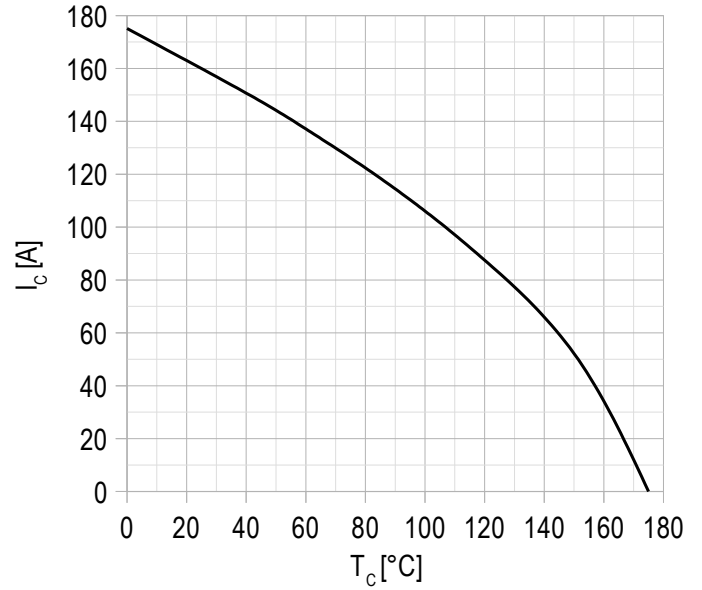
- Insulating material operating temperature 125°C max;
- Case temperature 125°C max;
- The recommended operating junction temperature $T_{vj\ op} = -40 \div +150^{\circ}\text{C}$.

Chart 1 – typ. output characteristic, IGBT.



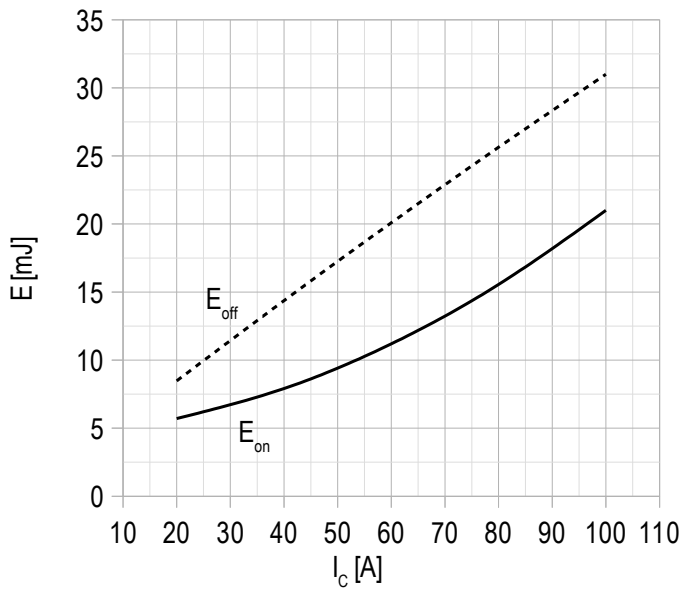
$V_{GE} = +15\text{ V}$.

Chart 2 – max. rated current vs temperature.



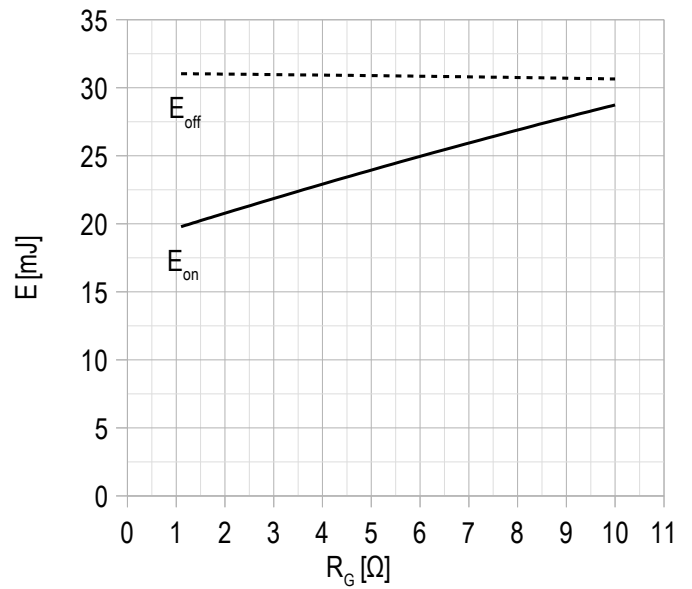
DC;
 $V_{GE} = +15\text{ V}$;
 $T_{vj(max)} = 175^\circ\text{C}$.

Chart 3 – typ. turn-on/off energy vs rated current, IGBT.



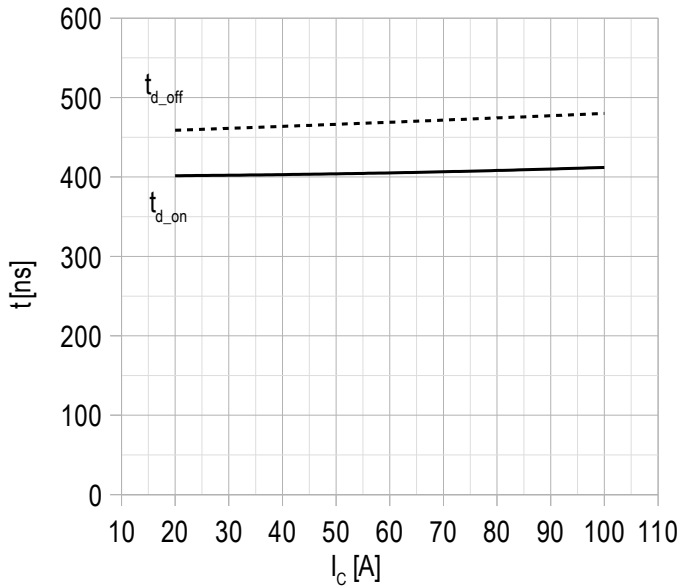
$V_{CE} = 920\text{ V}$;
 $V_{GE} = \pm 15\text{ V}$;
 $R_G = 2.2\ \Omega$;
 $L = 56\text{ nH}$;
 $T_{vj(max)} = 150^\circ\text{C}$.

Chart 4 – typ. turn-on/off energy vs gate resistance, IGBT.



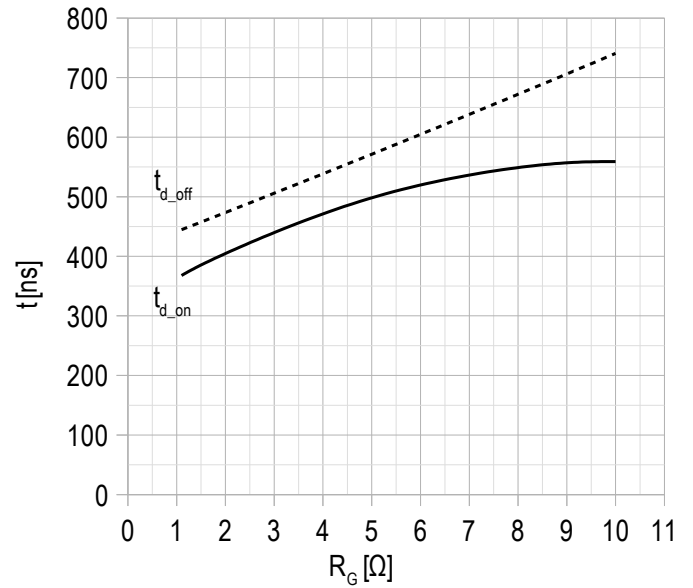
$V_{CE} = 920\text{ V}$;
 $V_{GE} = \pm 15\text{ V}$;
 $I_{Cmax} = 100\text{ A}$;
 $L = 56\text{ nH}$;
 $T_{vj(max)} = 150^\circ\text{C}$.

Chart 5 – typ. switching times vs rated current, IGBT.



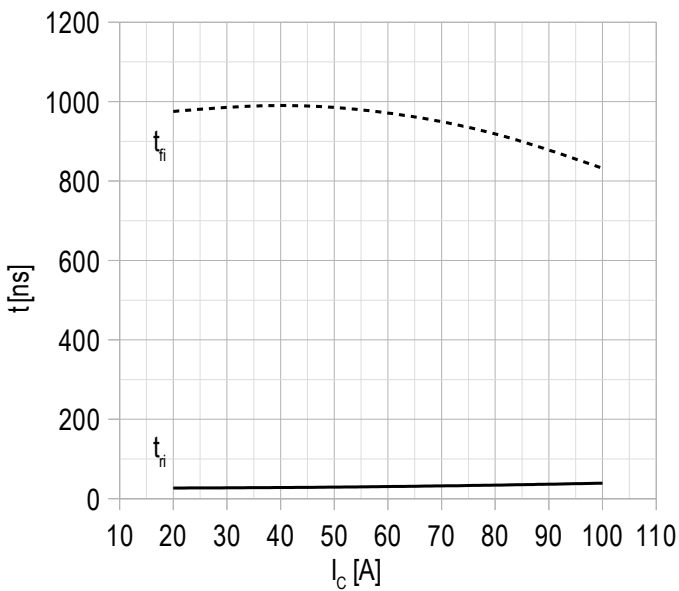
$V_{CE} = 920$ V;
 $V_{GE} = \pm 15$ V;
 $R_G = 2.2$ Ω ;
 $L = 56$ nH;
 $T_{vj(max)} = 150^\circ\text{C}$.

Chart 6 – typ. switching times vs gate resistance, IGBT.



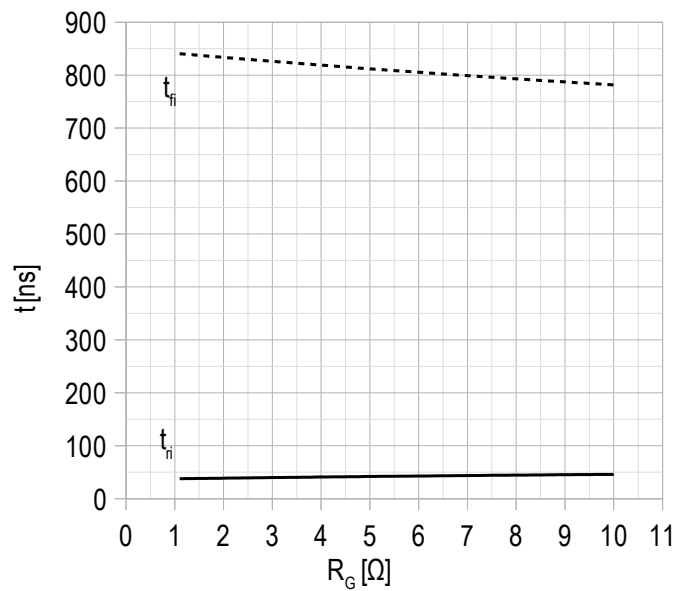
$V_{CE} = 920$ V;
 $V_{GE} = \pm 15$ V;
 $I_{Cmax} = 100$ A;
 $L = 56$ nH;
 $T_{vj(max)} = 150^\circ\text{C}$.

Chart 7 – typ. switching times vs rated current, IGBT.



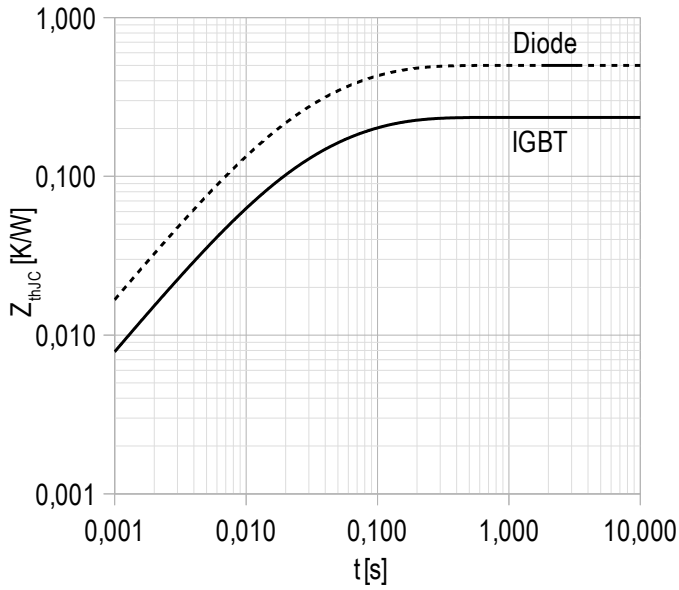
$V_{CE} = 920$ V;
 $V_{GE} = \pm 15$ V;
 $R_G = 2.2$ Ω ;
 $L = 56$ nH;
 $T_{vj(max)} = 150^\circ\text{C}$.

Chart 8 – typ. switching times vs gate resistance, IGBT.



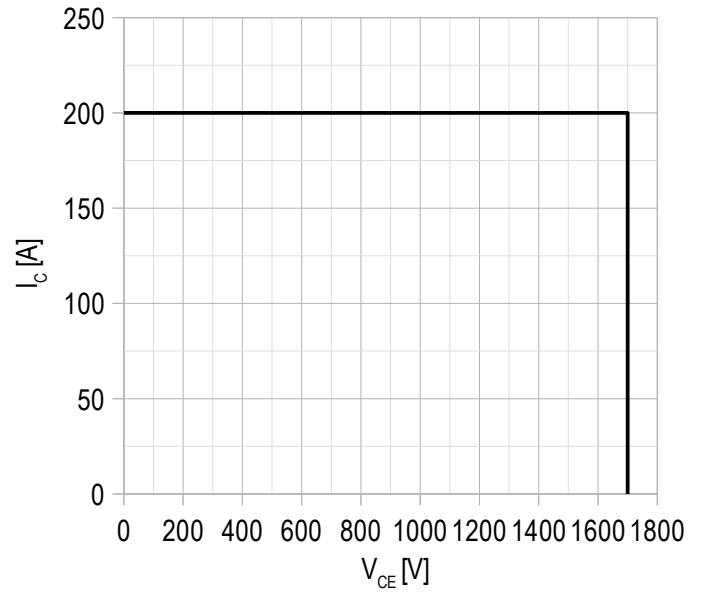
$V_{CE} = 920$ V;
 $V_{GE} = \pm 15$ V;
 $I_{Cmax} = 100$ A;
 $L = 56$ nH;
 $T_{vj(max)} = 150^\circ\text{C}$.

Chart 9 – max. transient thermal impedance.



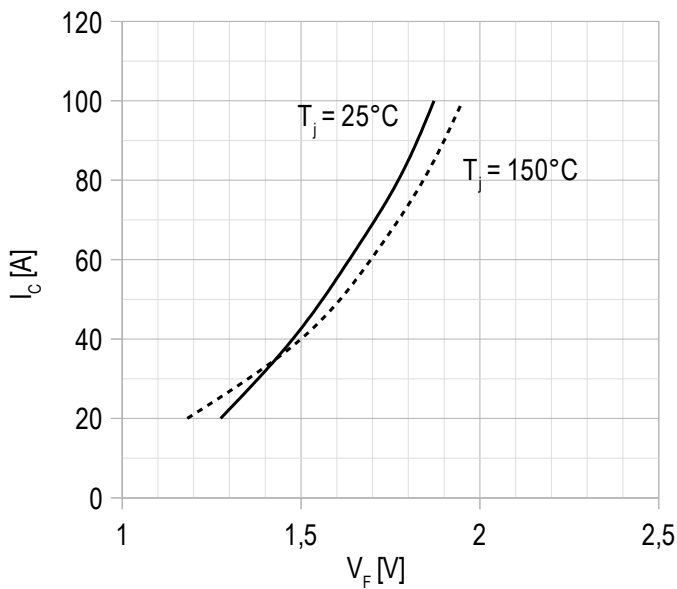
Single pulse;
V_{GE} = +15 V.

Chart 10 – RBSOA.



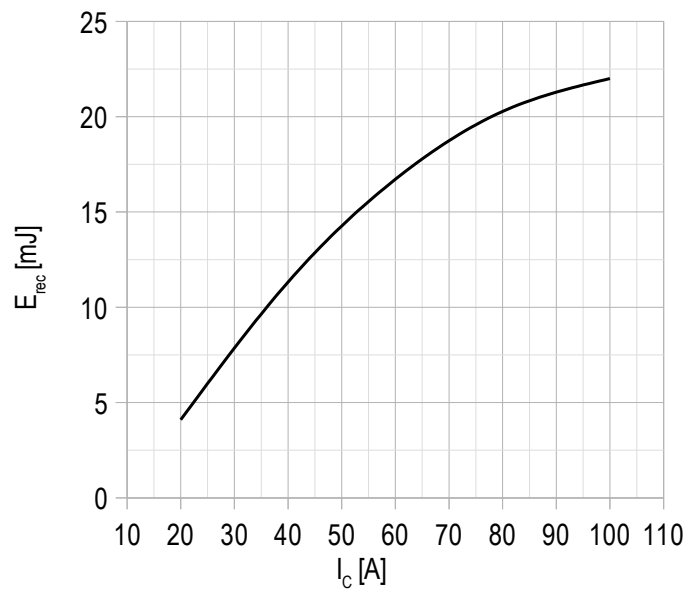
V_{CE max} = 1700 V;
V_{GE} = ±15 V;
I_{c max} = 2 * I_{c nom};
R_G = 2.2 Ω;
L = 56 nH.

Chart 11 – typ. output characteristic, FRD.



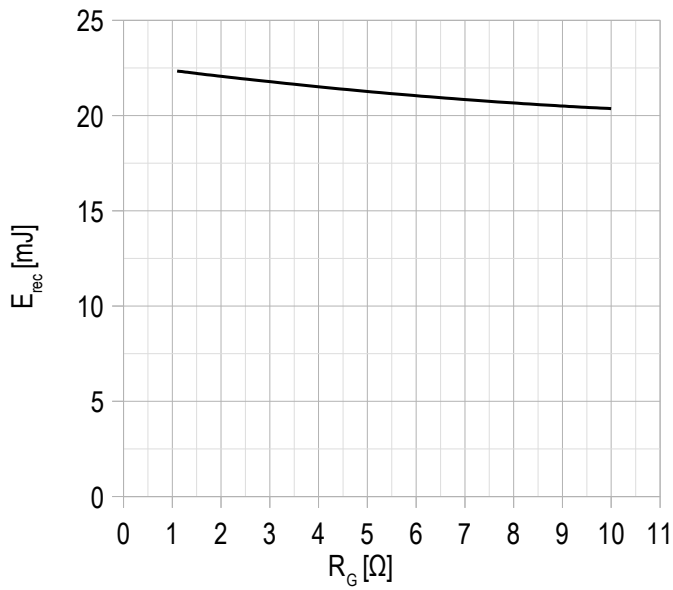
V_{GE} = +15 V.

Chart 12 – typ. switching losses vs rated current, FRD.



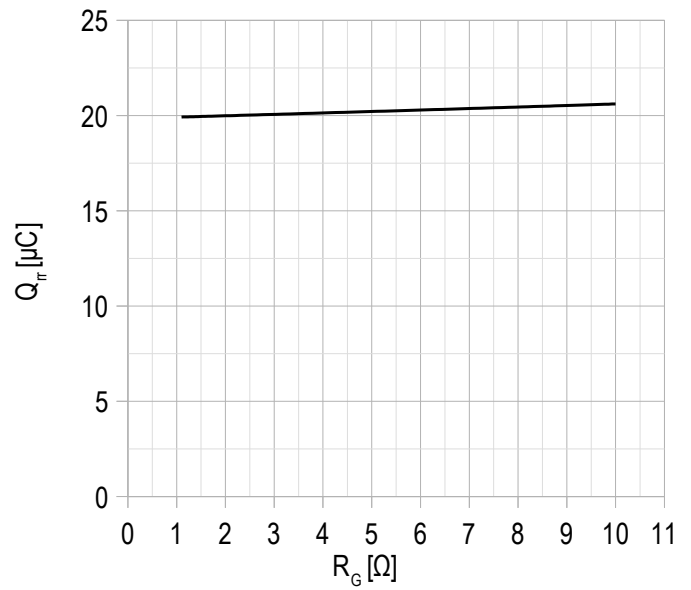
V_{GE} = ±15 V;
V_{CE} = 920 V;
L = 56 nH;
R_{G on} = 2.2 Ω;
T_{vj (max)} = 150°C.

Chart 13 – typ. switching losses vs gate resistance, FRD.



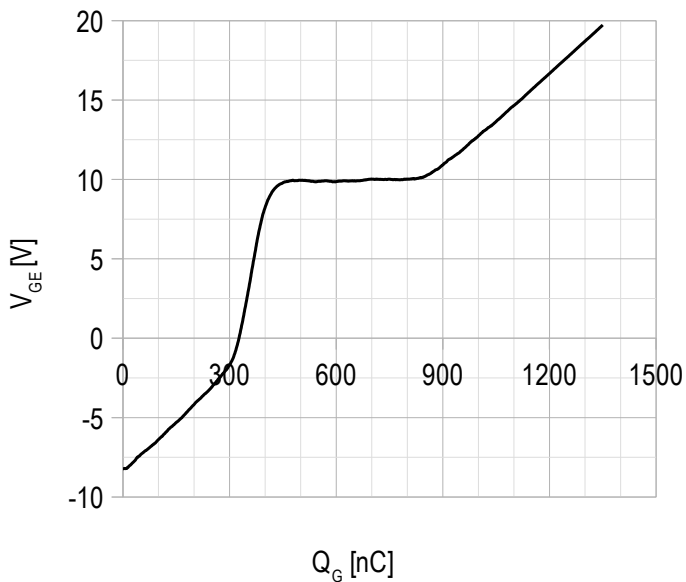
$V_{GE} = \pm 15$ V;
 $V_{CE} = 920$ V;
 $I_{C\ max} = 100$ A;
 $L = 56$ nH;
 $T_{vj\ (max)} = 150^\circ\text{C}$.

Chart 14 – typ. reverse recovered charge vs gate resistance, FRD.



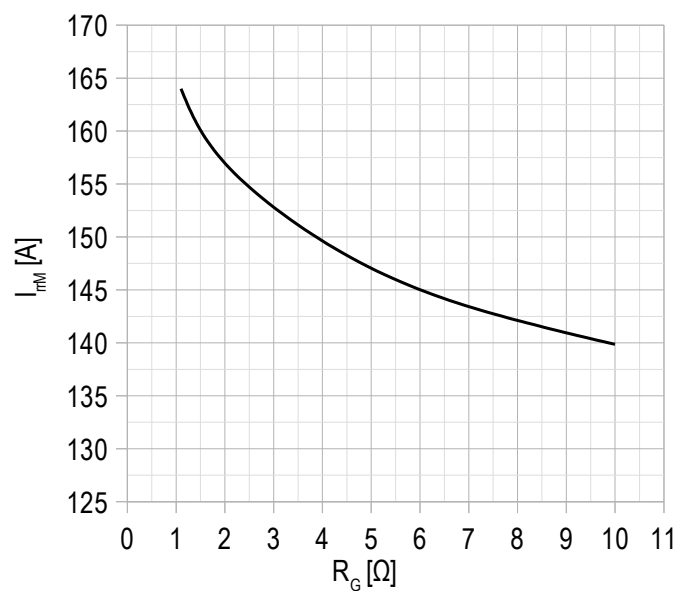
$V_{GE} = \pm 15$ V;
 $V_{CE} = 920$ V;
 $I_{C\ max} = 100$ A;
 $L = 56$ nH;
 $T_{vj\ (max)} = 150^\circ\text{C}$.

Chart 15 – typ. gate charge characteristic.



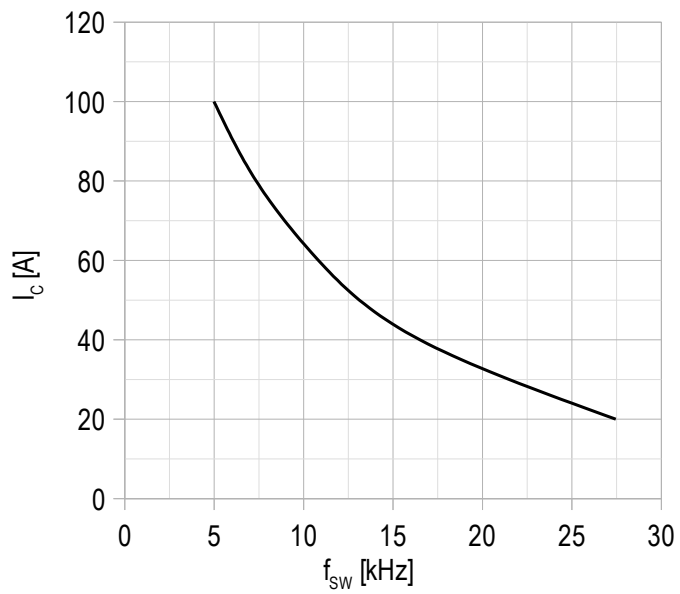
$I_C = 100$ A;
 $V_{CE} = 920$ V;
 $V_{GE} = -8 \div 15$ V.

Chart 16 – typ. reverse recovery current vs gate resistance FRD.



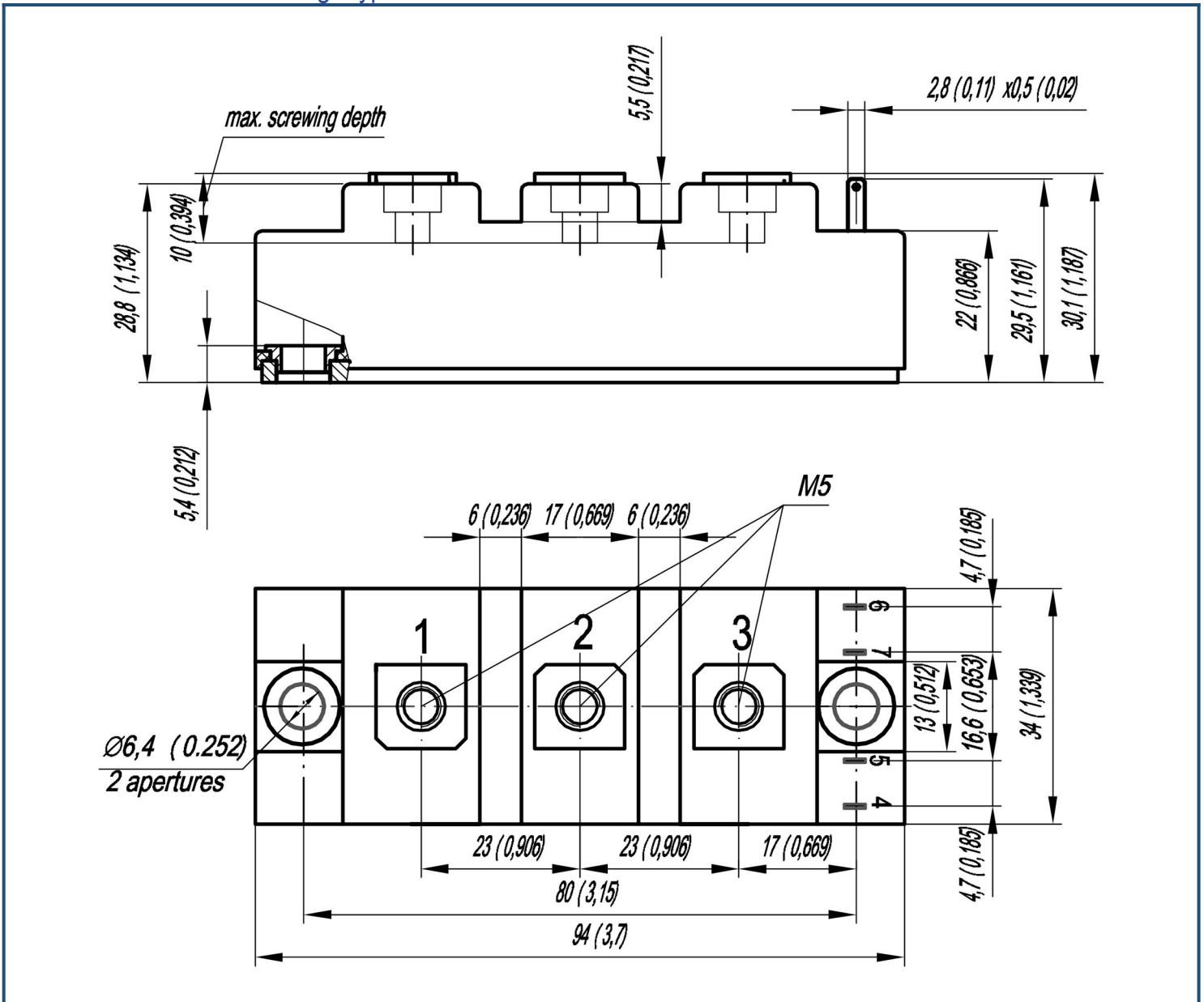
$V_{CE} = 920$ V;
 $V_{GE} = \pm 15$ V;
 $L = 56$ nH;
 $T_{vj\ (max)} = 150^\circ\text{C}$.

Chart 17 – typ. rated current vs frequency.



Duty cycle 50%;
 $T_c = 80\text{ }^\circ\text{C}$;
 $T_{vj(max)} = 175\text{ }^\circ\text{C}$.

Overall dimensions: Package type – FA



Part numbering guide

MIFA	-	HB	17	AA	-	100	N	
MIFA								IGBT module package type: FA
		HB						2 switches as Half-Bridge
		HC						1 switch as High-Side chopper
		LC						1 switch as Low-Side chopper
			17					Voltage rating ($V_{CES}/100$)
				AA				IGBT+FRD chipset modification
						100		Current Rating
							N	Climatic version: normal climate

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